

European Union Directive 2002/95/EC is known as RoHS, for “restriction of hazardous substances.” It required the EU member states to ban the use of six substances—lead (Pb), mercury (Hg), cadmium (Cd), hexavalent chromium (Cr<sup>6+</sup>), polybrominated biphenyls (PBB), and polybrominated diphenyl ethers (PBDE)—in new electrical and electronic equipment except in specific applications and industries that have been exempt. These exemptions are periodically reviewed and updated.

European Union Directive 2011/65/EU, known as RoHS Recast or RoHS 2, consolidated the original RoHS directive with its later amendments, including changes to the exemption list, and added new procedures and labeling. It has replaced the previous directive as the primary RoHS legislation and has extended it to products that had not been subject to the original directive.

No KOA products use asbestos, mercury, cadmium, hexavalent chromium, polybrominated biphenyls, or polybrominated diphenyl ethers. They are also free of perfluorooctane sulfonates (PFOS) and decabromodiphenyl ethers (deca-BDE), meeting the EU RoHS 2006/122/EC Directive.

A KOA part number includes a designator for the termination material, which is considered by RoHS 2 as one of the solder materials. Those parts with lead-free terminations (any designator other than ‘L’) are RoHS 2 compliant in all industries. Some of these parts may include lead in exempt applications. Please see the annexes for information on which exemptions apply to which series.

All KOA products are backward and forward compatible and may be used in both lead-free and lead-bearing solder processes. All products can withstand 10 seconds at 260°C temperatures for three cycles, have an MSL of 1 (with a recommended two-year shelf life for best practices), and meet J-STD-020C.

## Annex I

The following series are RoHS directive 2011/65/EU compliant (without any use of exemptions) for all industries when specified with any termination designator other than ‘L’:

AC(X)	AFS	BGR	BLR	BPR
BSR	BWR	CC	CCF	CCF1F
CCP	CF	CFS	CFP	CNN
CSR	CW	CWH	CWP	CZB
CZP	DN(X)	J	JL	KL73
KLC	KT11835	KTZ	LCM	LF
LFF	LKS	LP	LP73	LPC4235
LPC4545	LR	LR72	LT	LT73
LT73V	LWA	MF	MFS	MHL
MLT	MO	MOS	MRP	MRS
NPO	NPR1 (3.9mΩ - 62mΩ)	NPR2 (3.9mΩ - 62mΩ)	NV73 1E	NV73 1H
NV73DS	PAP	PGD	PGE	PSB
PSE	PSI	PSN	PSO	PV
PWW	R(X)A	RCS	RCT	RCU
RCW	RD(X)	RD41	RM41	RN41
RN73	RN73H	RNS	RT(X)	RW
SDR	SDS	SDT101	SDT73H	SDT73V
SF	SF45	SHDR	SL07	SL1 (3mΩ - 100mΩ)
SL2 (3mΩ - 360mΩ)	SL3	SLF	SLN	SLW1
SLZ	SPR	ST	TF16AT	TF(X)
TLR	TLRH	TLRZ	TPR	TSL
UR73	UR73D	WF	X5R	X7R
Y5V	Z			

## Annex II

The following series are RoHS directive 2011/65/EU compliant for all industries, using exemption 7(c)-I "Electrical and electronic components containing LEAD in a glass or ceramic other than dielectric ceramic in capacitors (piezoelectronic devices) or in a glass or ceramic matrix compound", when specified with any termination designator other than 'L':

BR	CN	CN_A	CN_H	CN_K
CN_N	CNB	CND	CN_RT	CN_KRT
CNZ	CPCN	CR	GS	HPC
HV73	KA	KQ	KQC	KQT
LA73	LPC4045	LPC9040E	LPC9040N	LPC10065
LPC12065	MCM	NPR1 (68mΩ - 22MΩ)	NPR2 (68mΩ - 22MΩ)	NT73
NV73 1J	NV73 2A	NV73 2B	NV73 2E	NV73 2J
NV73 2L	NV73 DL	NVD	PCF	PN
PT72	RCR	RF	RF25CC	RF26
RF73	RK1/4	RK1/2	RK1	RK26
RK73A	RK73B	RK73G	RK73H	RK73_RT
RK73Z	RK92	RKC	RKH	RKL
SA	SDT310	SDT310HCTP	SG73	SG73_RT
SG73P	SG73S	SL1 (110mΩ - 22MΩ)	SL2 (390mΩ - 22MΩ)	SR73
TF10BN	TF16SN	WK73		

## Annex III

The following series are RoHS directive 2011/65/EU compliant for all industries, using exemption 7(a) "LEAD in high melting temperature type solders (lead-based alloys containing 85% by weight or more lead)", when specified with any termination designator other than 'L':

KL32 (0.12μH - 0.82μH) KL32 (100μH - 330μH)

## Annex IV

The following series are RoHS directive 2011/65/EU compliant for all industries, using exemption 7(a) "LEAD in high melting temperature type solders (lead-based alloys containing 85% by weight or more lead)" and exemption 7(c)-I "Electrical and electronic components containing LEAD in a glass or ceramic other than dielectric ceramic in capacitors (piezoelectronic devices) or in a glass or ceramic matrix compound", when specified with any termination designator other than 'L':

KL32 (0.005μH - 0.10μH) KL32 (1.0μH - 82μH) MRGF16

## Annex V

The following series are RoHS directive 2011/65/EU compliant for the telecom industry, using exemption 7(b) "LEAD in solders for servers, storage and storage array systems, network infrastructure equipment for switching, signaling, transmission, and network management for telecommunications", when specified with the 'L' (SnPb) termination designator:

AC(X)	AFS	BGR	BLR	BPR
BSR	BWR	CC	CCF	CCF1F
CCP	CF	CFS	CFP	CNN
CSR	CW	CWH	CWP	CZB

CZP	DN(X)	J	JL	KL73
KLC	KT11835	KTZ	LCM	LF
LFF	LKS	LP	LP73	LPC4235
LPC4545	LR	LR72	LT	LT73
LT73V	LWA	MF	MFS	MHL
MLT	MO	MOS	MRP	MRS
NPO	NPR1 (3.9mΩ - 62mΩ)	NPR2 (3.9mΩ - 62mΩ)	NV73 1E	NV73 1H
NV73DS	PAP	PGD	PGE	PSB
PSE	PSI	PSN	PSO	PV
PWW	R(X)A	RCS	RCT	RCU
RCW	RD(X)	RD41	RM41	RN41
RN73	RN73H	RNS	RT(X)	RW
SDR	SDS	SDT101	SDT73H	SDT73V
SF	SF45	SHDR	SL07	SL1 (3mΩ - 100mΩ)
SL2 (3mΩ - 360mΩ)	SL3	SLF	SLN	SLW1
SLZ	SPR	ST	TF16AT	TF(X)
TLR	TLRH	TLRZ	TPR	TSL
UR73	UR73D	WF	X5R	X7R
Y5V	Z			

## Annex VI

The following series are RoHS directive 2011/65/EU compliant for the telecom industry, using exemption 7(b) "LEAD in solders for servers, storage and storage array systems, network infrastructure equipment for switching, signaling, transmission, and network management for telecommunications" and exemption 7(c)-I "Electrical and electronic components containing LEAD in a glass or ceramic other than dielectric ceramic in capacitors (piezoelectronic devices) or in a glass or ceramic matrix compound", when specified with the 'L' (SnPb) termination designator:

BR	CN	CN_A	CN_H	CN_K
CN_N	CNB	CND	CN_RT	CN_KRT
CNZ	CPCN	CR	GS	HPC
HV73	KA	KQ	KQC	KQT
LA73	LPC4045	LPC9040E	LPC9040N	LPC10065
LPC12065	MCM	NPR1 (68mΩ - 22MΩ)	NPR2 (68mΩ - 22MΩ)	NT73
NV73 1J	NV73 2A	NV73 2B	NV73 2E	NV73 2J
NV73 2L	NV73 DL	NVD	PCF	PN
PT72	RCR	RF	RF25CC	RF26
RF73	RK1/4	RK1/2	RK1	RK26
RK73A	RK73B	RK73G	RK73H	RK73_RT
RK73Z	RK92	RKC	RKH	RKL
SA	SDT310	SDT310HCTP	SG73	SG73_RT
SG73P	SG73S	SL1 (110mΩ - 22MΩ)	SL2 (390mΩ - 22MΩ)	SR73
TF10BN	TF16SN	WK73		

## Annex VII

The following series are RoHS directive 2011/65/EU compliant for the telecom industry, using exemption 7(a) "LEAD in high melting temperature type solders (lead-based alloys containing 85% by weight or more lead)" and exemption 7(b) "LEAD in solders for servers, storage and storage array systems, network infrastructure equipment for switching, signaling, transmission, and network management for telecommunications", when specified with the 'L' (SnPb) termination designator:

KL32 (0.12 $\mu$ H - 0.82 $\mu$ H) KL32 (100 $\mu$ H - 330 $\mu$ H)

## Annex VIII

The following series are RoHS directive 2011/65/EU compliant for the telecom industry, using exemption 7(a) "LEAD in high melting temperature type solders (lead-based alloys containing 85% by weight or more lead)", exemption 7(b) "LEAD in solders for servers, storage and storage array systems, network infrastructure equipment for switching, signaling, transmission, and network management for telecommunications", and exemption 7(c)-I "Electrical and electronic components containing LEAD in a glass or ceramic other than dielectric ceramic in capacitors (piezoelectronic devices) or in a glass or ceramic matrix compound", when specified with the 'L' (SnPb) termination designator:

KL32 (0.005 $\mu$ H - 0.10 $\mu$ H) KL32 (1.0 $\mu$ H - 82 $\mu$ H) MRGF16



Matthew L. Kervin  
Product/Application Engineer  
KOA Speer Electronics, Inc.  
199 Bolivar Drive  
Bradford, PA 16701  
(814) 362-5536